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United States Patent [19]

Wada

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[45] **Date of Patent: ** Jul. 20, 1993**

[54] **EARPHONE**

[75] Inventor: **Joh Wada**, Tokyo, Japan

[73] Assignee: **Sony Corporation**, Tokyo, Japan

[**] Term: **14 Years**

[21] Appl. No.: **797,278**

[22] Filed: **Nov. 25, 1991**

[30] **Foreign Application Priority Data**

Jun. 17, 1991 [JP] Japan 3-18003

[52] **U.S. Cl.** **D14/223**

[58] **Field of Search** D14/204–206, D14/223; D29/19; 181/129; 379/430; 381/25, 68, 68.7, 69.2, 183, 187

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[57] **CLAIM**

The ornamental design for an earphone, as shown and described.

DESCRIPTION

FIG. **1** is a top plan view of an earphone, showing my new design;

FIG. **2** is a left-side elevational view thereof;

FIG. **3** is a front elevational view thereof;

FIG. **4** is a right-side elevational view thereof;

FIG. **5** is a rear elevational view thereof;

FIG. **6** is a bottom plan view thereof;

FIG. **7** is a right-side perspective view thereof; and,

FIG. **8** is a left-side perspective view thereof.

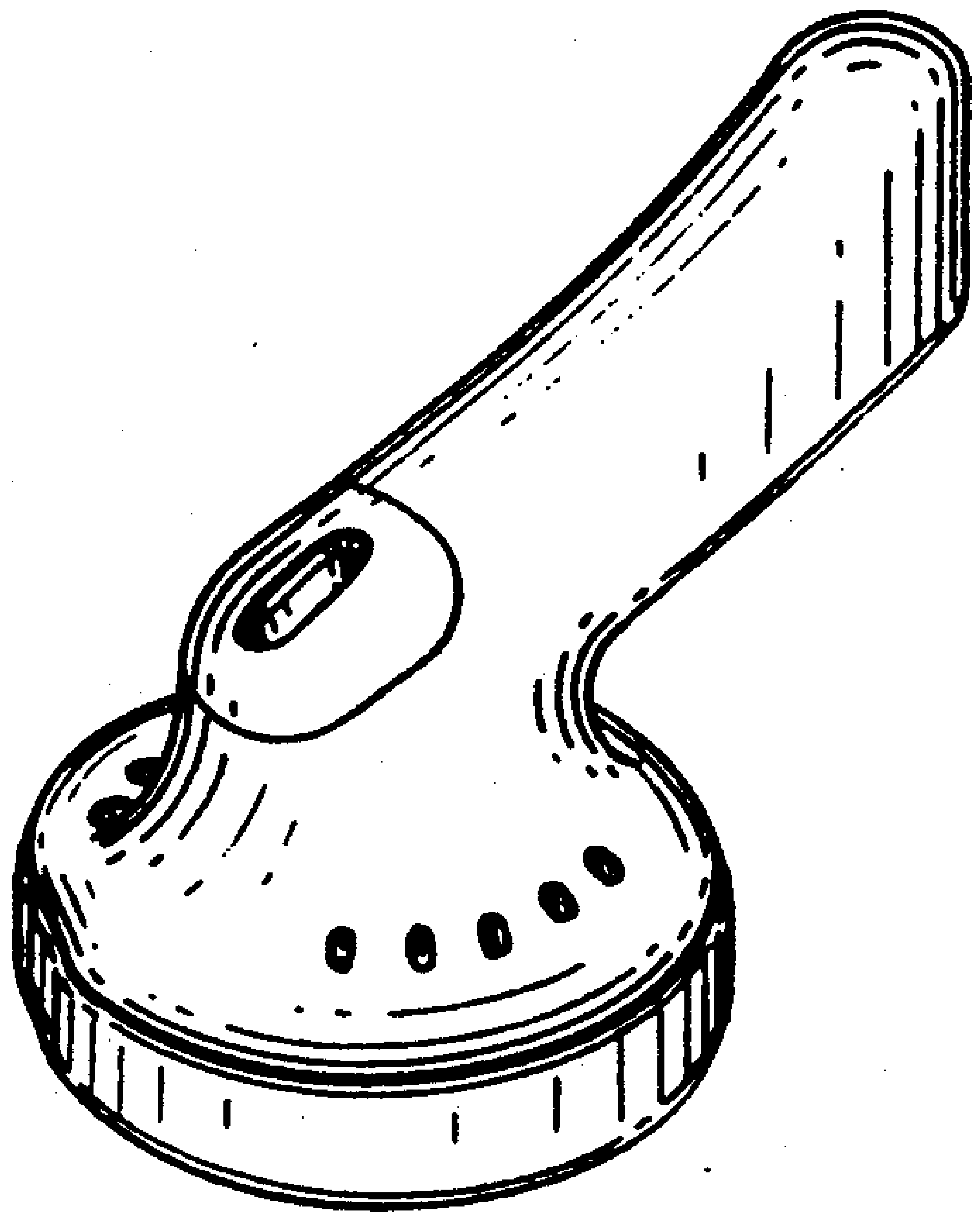


FIG. 1

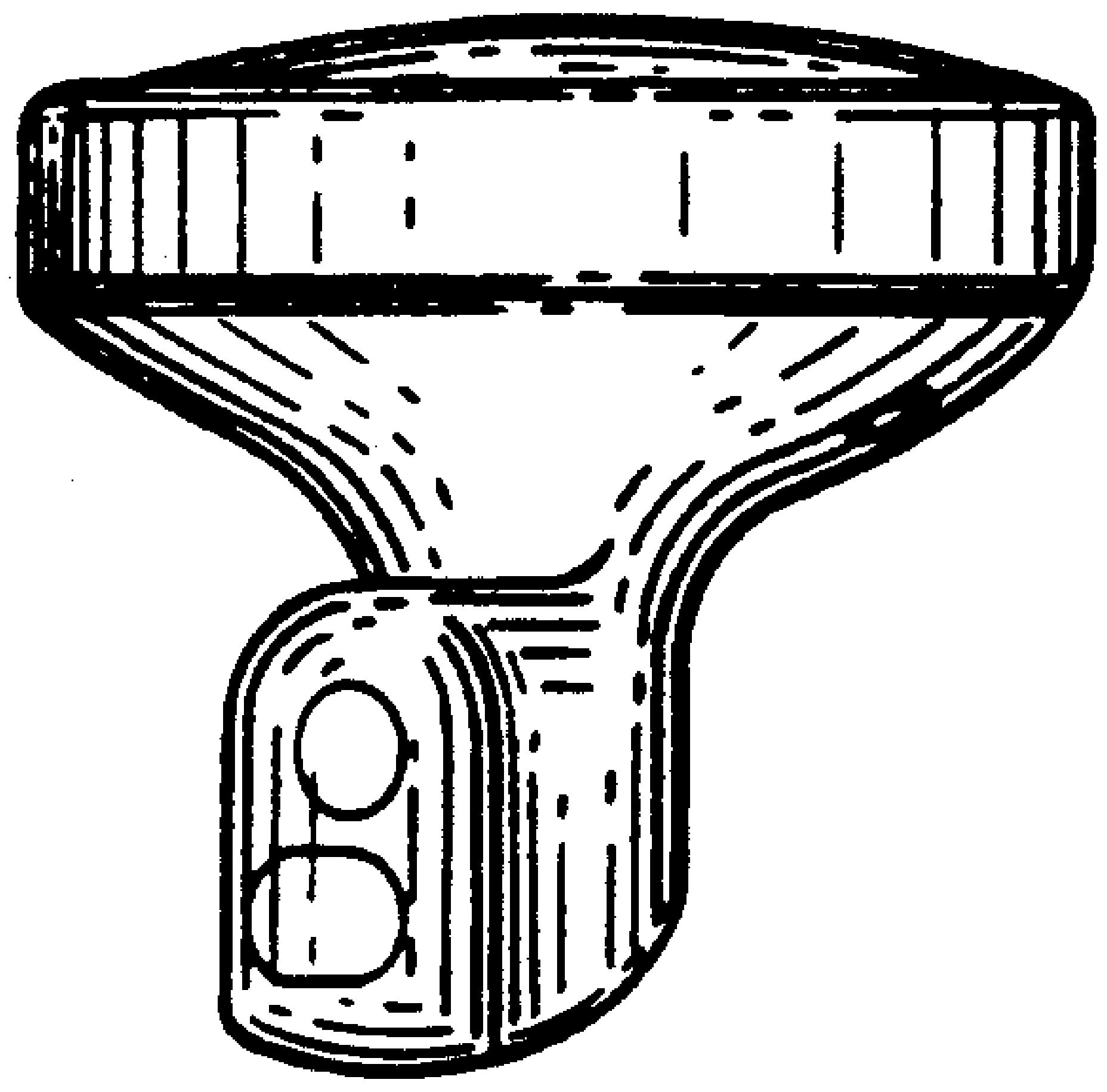
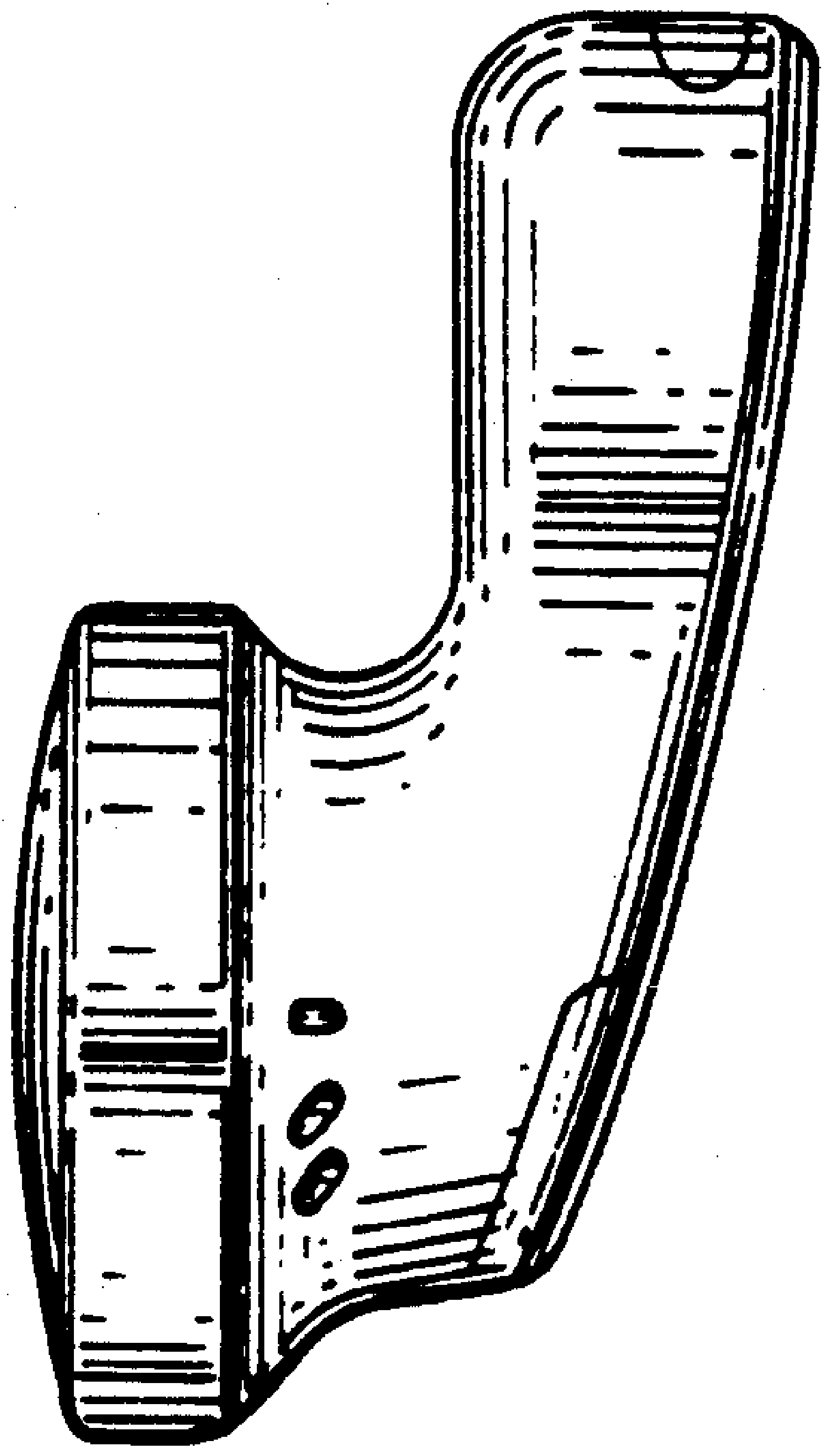


FIG. 2



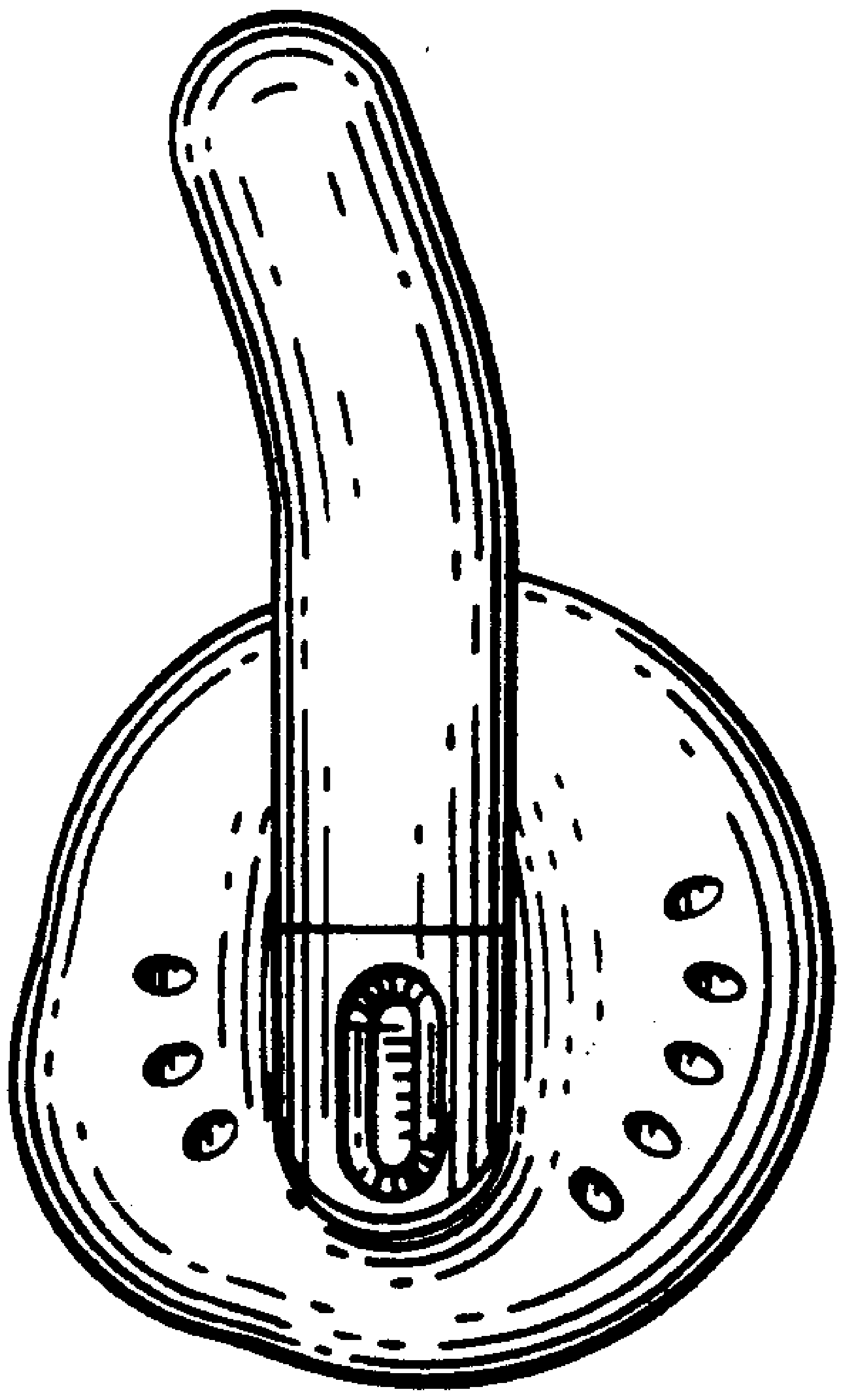


FIG. 3

FIG. 4

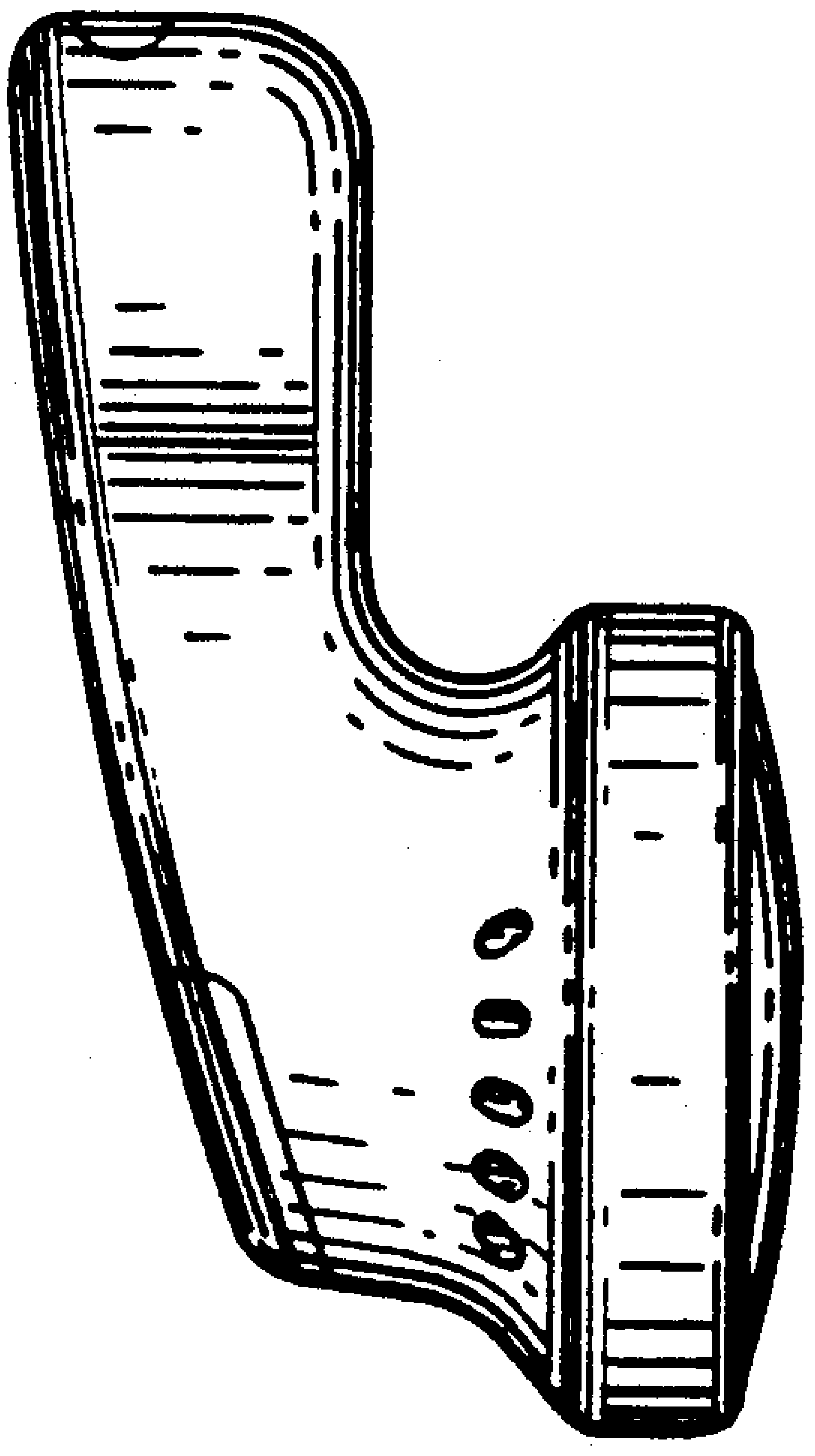


FIG. 5

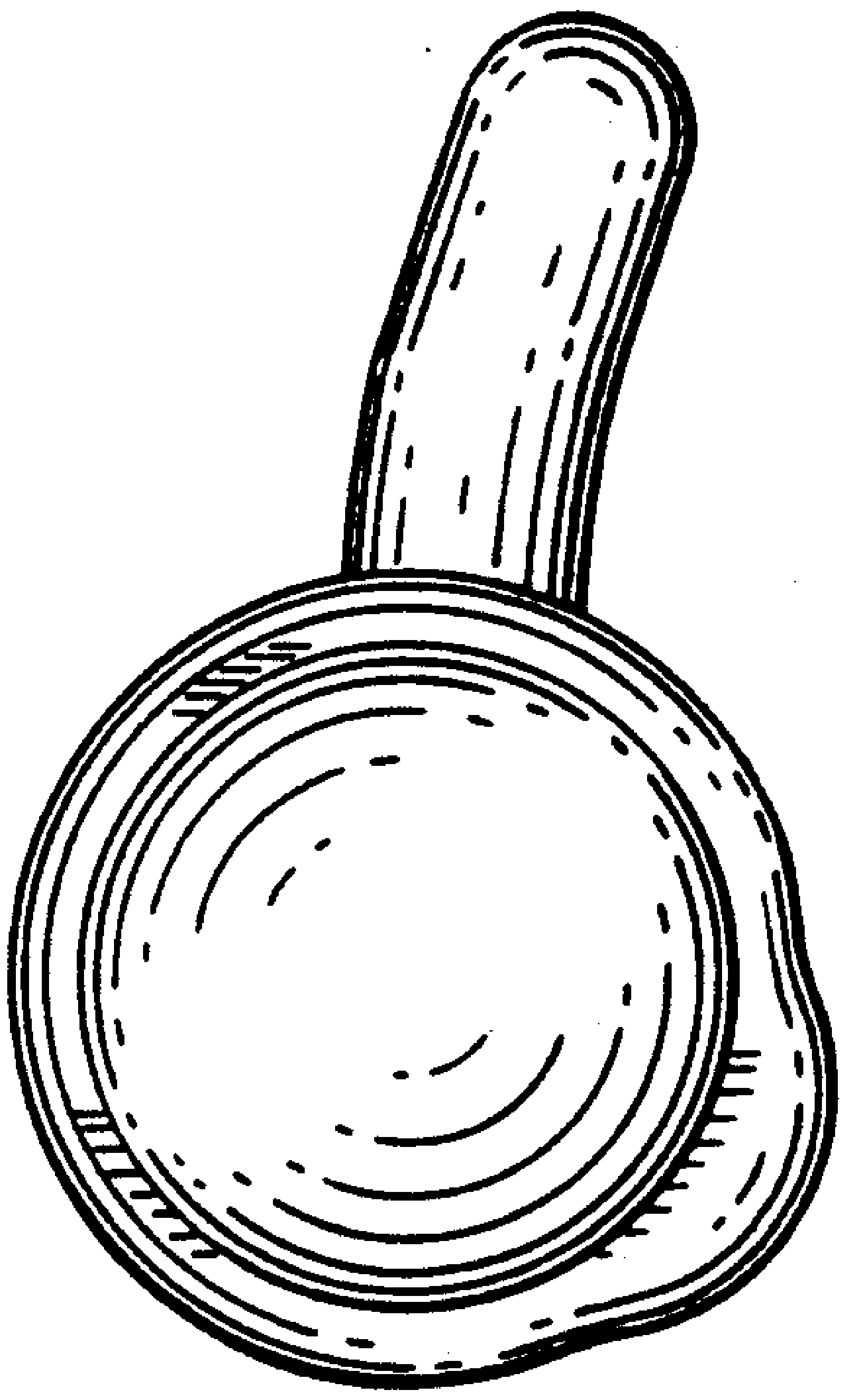


FIG. 6

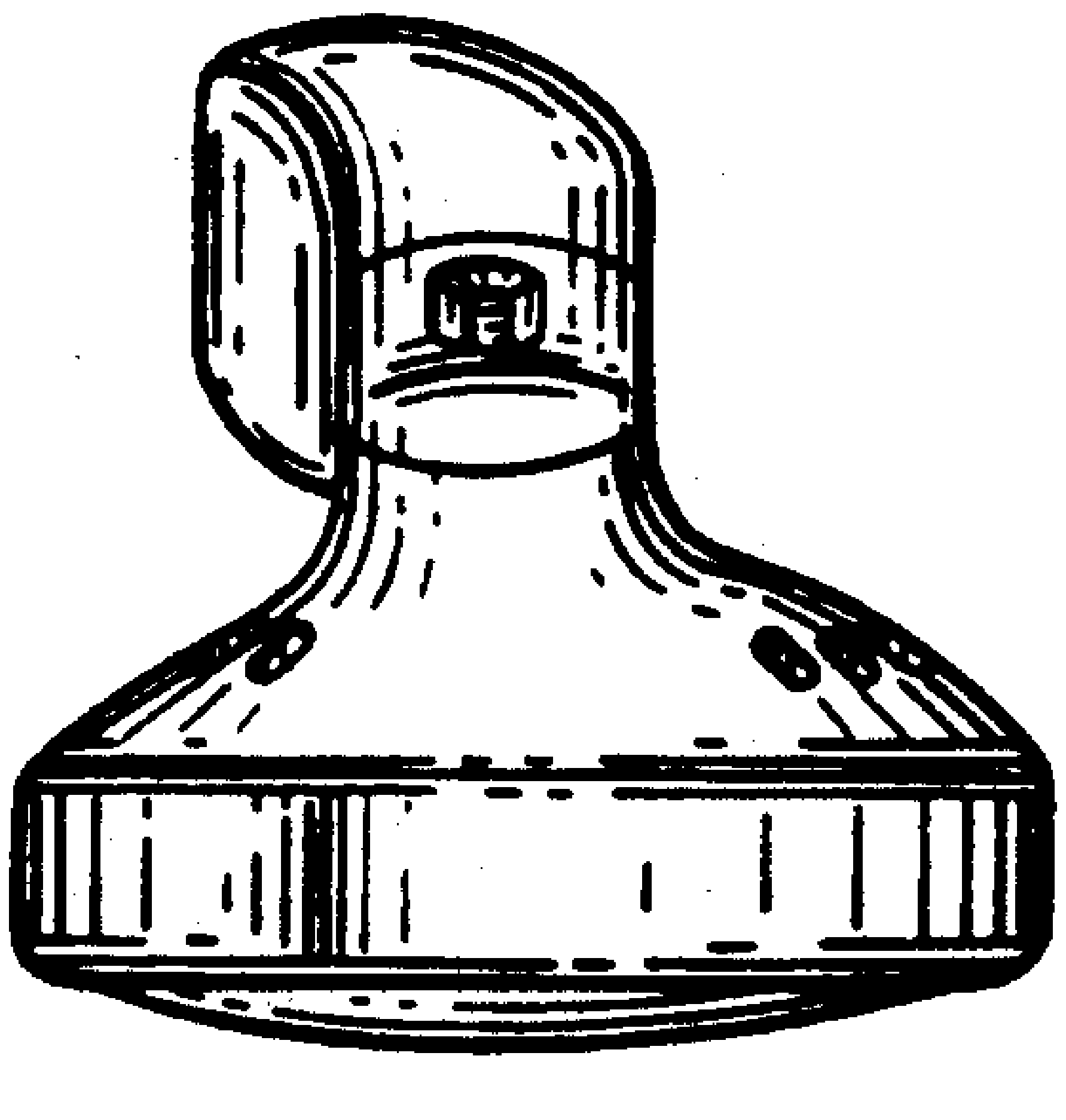


FIG. 8

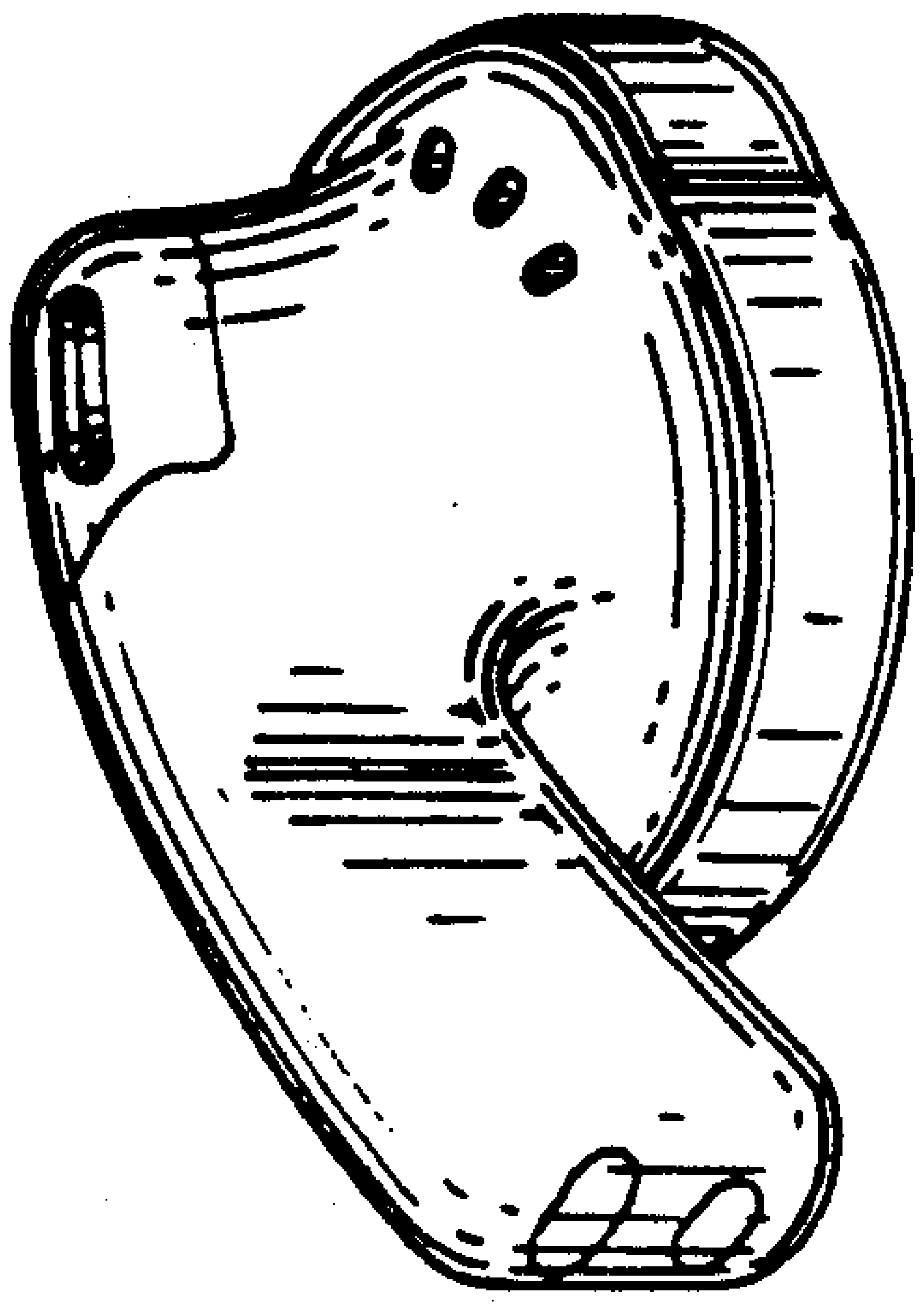


FIG. 7